HARRIS

HC-5509B

December 1990

Subscriber Line Interface Circuit - SLIC

Features

- DI Monolithic High Voltage Process
- Compatible with Worldwide PBX and CO Performance Requirements
- Controlled Supply of Battery Feed Current With Programmable Current Limit
- Operates with 5 Volt Positive Supply (VB+)
- Internal Ring Relay Driver and a Utility Relay Driver
- High Impedance Mode for Subscriber Loop
- High Temperature Alarm Output
- Low Power Consumption During Standby Functions
- Switch Hook, Ground Key, and Ring Trip Detection
- Selective Power Denial to Subscriber
- Voice Path Active During Power Denial
- On Chip Op-Amp for 2 Wire Impedance Matching

Applications

- Solid State Line Interface Circuit for PBX or Central Office Systems, Digital Loop Carrier Systems
- Hotel/Motel Switching Systems
- Direct Inward Dialing (DID) Trunks
- Voice Messaging PBX's
- High Voltage 2W/4W, 4W/2W Hybrid

Description

The HC-5509B telephone Subscriber Line Interface Circuit integrates most of the BORSCHT functions on a monolithic IC. The device is manufactured in a Dielectric Isolation (DI) process and is designed for use as a high voltage interface between the traditional telephone subscriber pair (Tip and Ring) and the low voltage filtering and coding/decoding functions of the line card. Together with a secondary protection diode bridge and "feed" resistors, the device will withstand 1000V lightning induced surges, in plastic packages. The SLIC also maintains specified transmission performance in the presence of externally induced longitudinal currents. The BORSCHT functions that the SLIC provides are:

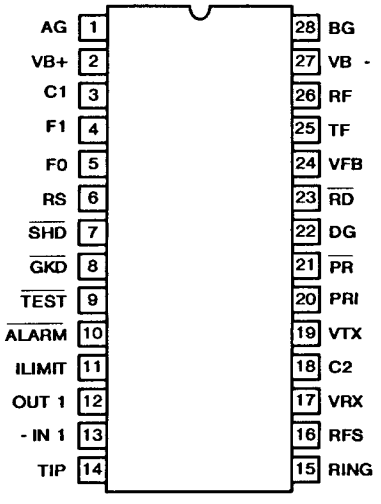
- Battery Feed with Subscriber Loop Current Limiting
- Overvoltage Protection
- Ring Relay Driver
- Supervisory Signaling Functions
- Hybrid Functions (with External Op-Amp)
- Test (or Battery Reversal) Relay Driver

In addition, the SLIC provides selective denial of power to subscriber loops, a programmable subscriber loop current limit from 20 to 60mA, a thermal shutdown with an alarm output and line fault protection. Switch hook detection, ring trip detection and ground key detection functions are also incorporated in the SLIC device.

The HC-5509B SLIC is available in a 28 pin Dual-in-Line Ceramic or Plastic package, a 44 pin Plastic Leaded Chip Carrier, or in a 28 Pin SOIC. It is ideally suited for line card designs in PBX and CO systems, replacing traditional transformer solutions.

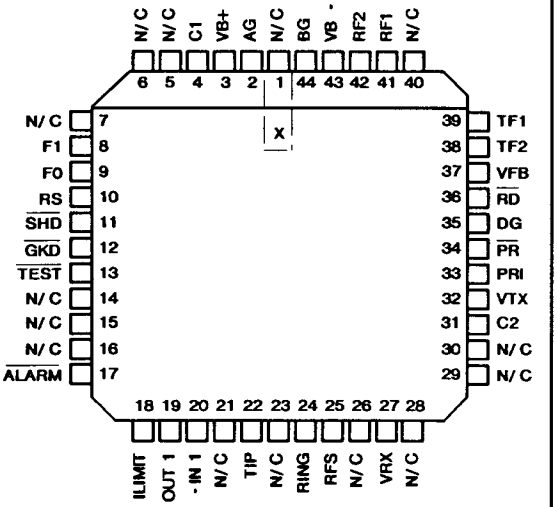
Pinouts

HC1-5509B, HC3-5509B, & HC9P5509B
TOP VIEW



TRUTH TABLE		
F1	F0	Action
0	0	Normal Loop Feed
0	1	$\overline{RD}$ Active
1	0	Power Down Latch RESET
1	0	Power on RESET
1	1	Loop Power Denial Active

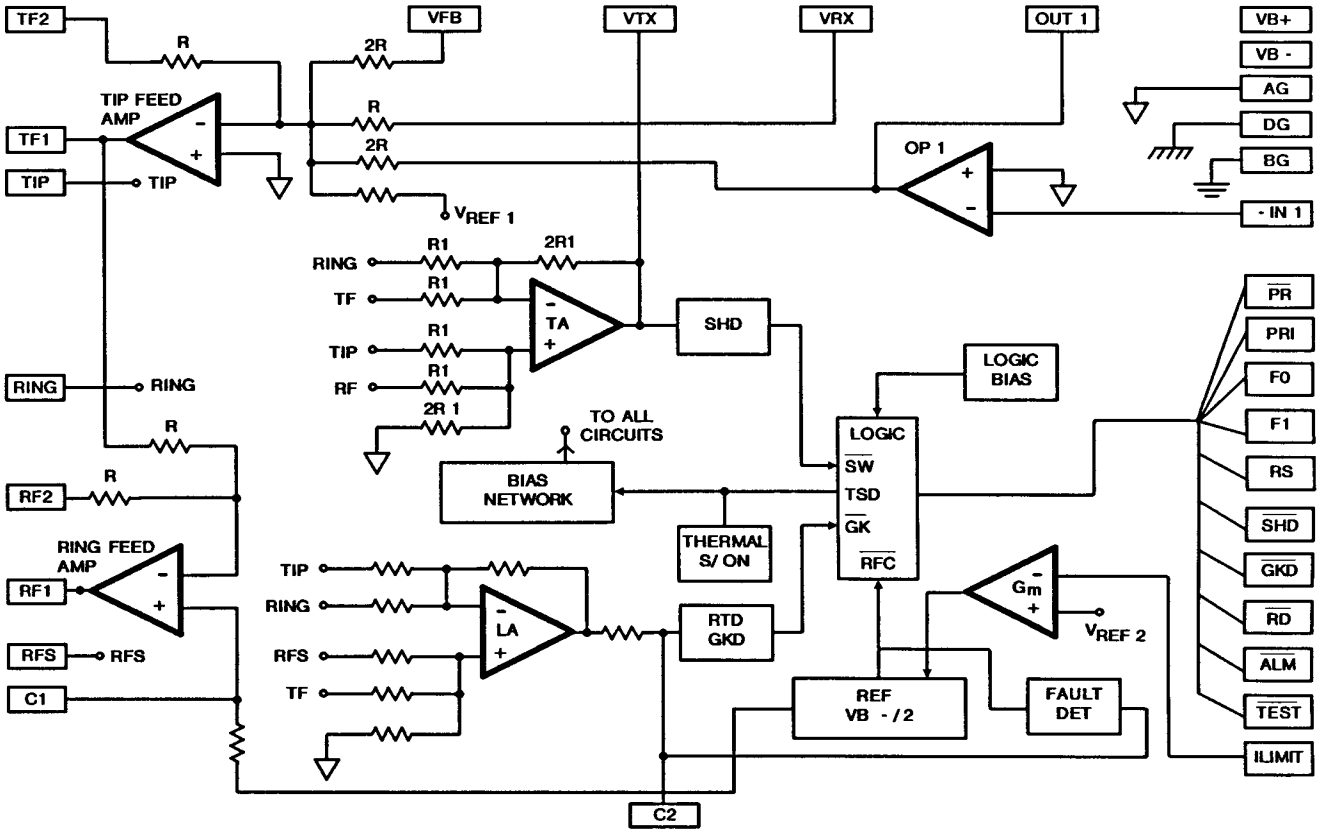
HC4P5509B
TOP VIEW



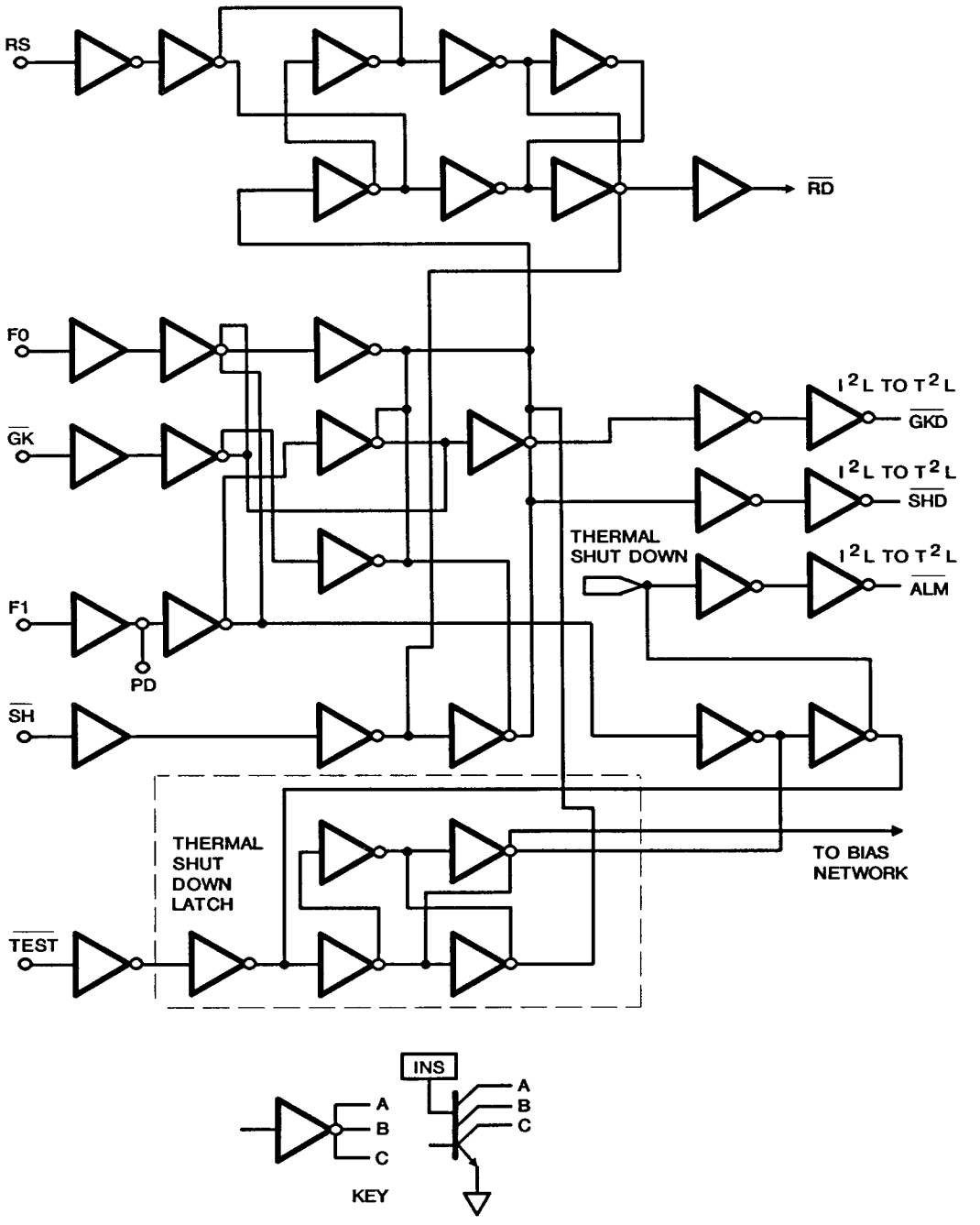
CAUTION: These devices are sensitive to electrostatic discharge. Proper I.C. handling procedures should be followed.

File Number **2799**

Functional Diagram



Logic Diagram



Absolute Maximum Ratings (Note 1)

Relay Drivers ..... -0.5V to +15V
Maximum Supply Voltages (VB+) ..... -0.5V to +7V
(VB+)-(VB-) ..... +75V
Storage Temperature Range ..... -65°C to +150°C
Junction Temperature Ceramic ..... +175°C
Junction Temperature Plastic ..... +150°C

Recommended Operating Conditions

Relay Drivers ..... +5V to +12V
Positive Power Supply (VB+) ..... +5V ±5%
Negative Power Supply (VB-) ..... -42V to -58V
Loop Resistance (RL) ..... 200Ω to 1750Ω*
Operating Temperature Range
HC-5509B-5 ..... 0°C to +75°C
HC-5509B-9 ..... -40°C to +85°C

*Note: May Be Extended to 1900Ω With Application Circuit.

Electrical Specificatons Unless Otherwise Stated, Typical Parameters are at T_A = +25°C, Min-Max Parameters are over Operating Temperature Range. VB- = -48V, VB+ = +5V, AG = DG = BG = 0V. All A.C. Parameters are specified at 600Ω 2 wire terminating impedance.

A.C. Transmission Parameters

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
RX Input Impedance	300Hz to 3.4kHz (Note 2)	-	100	-	K
TX Output Impedance		-	-	20	Ω
4W Input Overload Level	300Hz to 3.4kHz RL = 1200Ω, 600Ω Reference	+1.5	-	-	V_{Pk}
2W Return Loss	Balanced for 600Ω (Note 2)				
SRL LO		26	35	-	dB
ERL		30	40	-	dB
SRL HI		30	40	-	dB
2W Longitudinal to Metallic Balance	Per ANSI/IEEE STD 455-1976 (Note 2)				
Off Hook	300Hz to 3400Hz	58	63	-	dB
4W Longitudinal Balance					
Off Hook	300Hz to 3400Hz (Note 2)	50	55	-	dB
Low Frequency Longitudinal Balance	R.E.A. Test Circuit	-	-	-67	dBmp
	I_{LINE} = .040A T_A = +25°C (Note 2)	-	-	23	dBrnc
Longitudinal Current Capability	I_{LINE} = .040A T_A = +25°C (Note 2)	-	-	30	mArms
Insertion Loss	0dBm at 1kHz, Referenced 600Ω				
2W/4W		-	±0.05	±0.2	dB
4W/2W		-	±0.05	±0.2	dB
4W/4W		-	-	±.12	dB
Frequency Response	300Hz to 3400Hz (Note 2) Referenced to Absolute Level at 1kHz, 0dBm Referenced 600	-	±0.02	±0.05	dB
Level Linearity	Referenced to -10dBm (Note 2)				
2W to 4W and 4W to 2W	+3 to -40dBm	-	-	±0.05	dB
	-40 to -50dBm	-	-	±0.1	dB
	-50 to -55dBm	-	-	±0.3	dB
Absolute Delay	(Note 2)				
2W/4W	300Hz to 3400Hz	-	-	1	µs
4W/2W	300Hz to 3400Hz	-	-	1	µs
4W/4W	300Hz to 3400Hz	-	-	1.5	µs
Transhybrid Loss, THL	(Note 2) See Figure 1	-	40	-	dB
Total Harmonic Distortion	Reference Level 0dBm at 600Ω				
2W/4W, 4W/2W, 4W/4W	300Hz to 3400Hz (Note 2)	-	-	-52	dB
Idle Channel Noise	(Note 2)				
2W and 4W	C-Message	-	-	5	dBrnc
	Psophometric	-	-	-85	dBmp
	3kHz Flat	-	-	15	dBrn

Electrical Specificatons Unless Otherwise Stated, Typical Parameters are at T_A = +25°C, Min-Max Parameters are over Operating Temperature Range. VB- = -48V, VB+ = +5V, AG = DG = BG = 0V. All A.C. Parameters are specified at 600Ω 2 wire terminating impedance.

A.C. Transmission Parameters (Continued)

PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNITS
Power Supply Rejection Ratio	(Note 2)				
VB+ to 2W	30Hz to 200Hz, RL = 600Ω	20	29	-	dB
VB+ to 4W		20	29	-	dB
VB- to 2W		20	29	-	dB
VB- to 4W		20	29	-	dB
VB+ to 2W	200Hz to 16kHz	30	-	-	dB
VB+ to 4W		30	-	-	dB
VB- to 2W		20	25	-	dB
VB- to 4W		20	25	-	dB
Ring Sync Pulse Width		50	-	500	µs

D.C. Parameters

PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNITS
Loop Current Programming					
Limit Range		20	40	60	mA
Accuracy		10	-	-	%
Loop Current During Power Denial	RL = 200Ω	-	±3	±5	mA
Fault Currents					
TIP to Ground		-	45	-	mA
RING to Ground		-	60	-	mA
TIP and RING to Ground		-	105	-	mA
Switch Hook Detection Threshold		-	12	15	mA
Ground Key Detection Threshold		-	12	15	mA
Thermal $\overline{\text{ALARM}}$ Output	Safe Operating Die Temperature Exceeded	140	-	160	°C
Ring Trip Detection Threshold	V_{RING} = 105V_{RMS}, f_{RING} = 20Hz	-	12	15	mA
Ring Trip Detection Period		-	100	150	ms
Dial Pulse Distortion		-	0.1	0.5	ms
Relay Driver Outputs	I_{OL} ($\overline{PR}$) = 60mA, I_{OL} ($\overline{RD}$) = 30mA				
On Voltage V_{OL}		-	0.2	0.5	V
Off Leakage Current	V_{OH} = 13.2V	-	±10	±100	µA
TTL/CMOS Logic Inputs ($\overline{F0}$, F1, RS, $\overline{TEST}$, PRI)					
Logic '0' V_{IL}		-	-	0.8	V
Logic '1' V_{IH}		2.0	-	5.5	V
Input Current ($\overline{F0}$, F1, RS, $\overline{TEST}$, PRI)	0V ≤ VIN ≤ 5V	-	-	±100	µA
Logic Outputs					
Logic '0' V_{OL}	I_{LOAD} = 800µA	-	0.1	0.5	V
Logic '1' V_{OH}	I_{LOAD} = 40µA	2.7	-	-	V
Power Dissipation On Hook	Relay Drivers Off	-	200	-	mW
I_{B+}	V_{B+} = +5.25V, V_{B-} = -58V, R_{LOOP} = ∞	-	-	6	mA
I_{B-}	V_{B+} = +5.25V, V_{B-} = -58V, R_{LOOP} = ∞	-6	-	-	mA

Electrical Specificatons Unless Otherwise Stated, Typical Parameters are at T_A = +25°C, Min-Max Parameters are over Operating Temperature Range. VB- = -48V, VB+ = +5V, AG = DG = BG = 0V. All A.C. Parameters are specified at 600Ω 2 wire terminating impedance.

Uncommited Op Amp Parameters

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Input Offset Voltage		-	±5	-	mV
Input Offset Current		-	±10	-	nA
Differential Input Resistance	(Note 2)	-	1	-	MΩ
Output Voltage Swing	RL = 10K	-	±3	-	V_{P-P}
Small Signal GBW	(Note 2)	-	1	-	MHz

NOTES:

1. Absolute maximum ratings are limiting values, applied individually, beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied.
2. These parameters are controlled by design or process parameters and are not directly tested. These parameters are characterised upon initial design release, upon design changes which would affect these characteristics, and at intervals to assure product quality and specification compliance.

Pin Descriptions

DIP	PLCC	SYMBOL	DESCRIPTION
1	2	AG	Analog Ground - To be connected to zero potential. Serves as a reference for the transmit output and receive input terminals.
2	3	VB+	Positive Voltage Source - Most Positive Supply.
3	4	C1	Capacitor #C1 - An external capacitor to be connected between this terminal and analog ground. Required for proper operation of the loop current limiting function.
4	8	F1	Function Address #1 - A TTL and CMOS compatible input used with F0 function address line to externally select logic functions. The three selectable functions are mutually exclusive. See Truth Table on page1. F1 should be toggled high after power is applied.
5	9	F0	Function Address #0 - A TTL and CMOS compatible input used with F1 function address line to externally select logic functions. The three selectable functions are mutually exclusive. See Truth Table on page 1.
6	10	RS	Ring Synchronization Input - A TTL - compatible clock input. The clock is arranged such that a positive pulse (50 - 500µs) occurs on the zero crossing of the ring voltage source, as it appears at the RFS terminal. For Tip side injected systems, the RS pulse should occur on the negative going zero crossing and for Ring injected systems, on the positive going zero crossing. This ensures that the ring delay activates and deactivates when the instantaneous ring voltage is near zero. If synchronization is not required, the pin should be tied to +5.
7	11	$\overline{SHD}$	Switch Hook Detection - An active low LS TTL compatible logic output. A line supervisory output.
8	12	$\overline{GKD}$	Ground Key Detection - An active low LS TTL compatable logic output. A line supervisory output.
9	13	$\overline{TEST}$	A TTL logic input. A low on this pin will set a latch and keep the SLIC in a power down mode until the proper F1, F0 state is set and will keep $\overline{ALARM}$ low. See Truth Table on page 1.
10	17	$\overline{ALARM}$	A LS TTL compatable active low output which responds to the thermal detector circuit when a safe operating die temperature has been exceeded. When $\overline{TEST}$ is forced low by an external control signal, $\overline{ALARM}$ is latched low until the proper F1, F0 state and $\overline{TEST}$ input is brought high. The $\overline{ALARM}$ can be tied directly to the $\overline{TEST}$ pin to power down the part when a thermal fault is detected and then reset with F0, F1. See Truth Table on page 1. It is possible to ignore transient thermal overload conditions in the SLIC by delaying the response to the $\overline{TEST}$ pin from the $\overline{ALARM}$. Care must be exercised in attempting this as continued thermal overstress may reduced component life.
11	18	ILIMIT	Loop Current Limit - Voltage on this pin sets the short loop current limiting conditions using a resistive voltage divider.
12	19	OUT1	The analog output of the spare operational amplier.
13	20	-IN1	The inverting analog input of the spare operational amplier.
14	22	TIP	An analog input connected to the TIP (more positive) side of the subscriber loop through a feed resistor and ring relay contact. Functions with the RING terminal to receive voice signals from the telephone and for loop monitoring purpose.

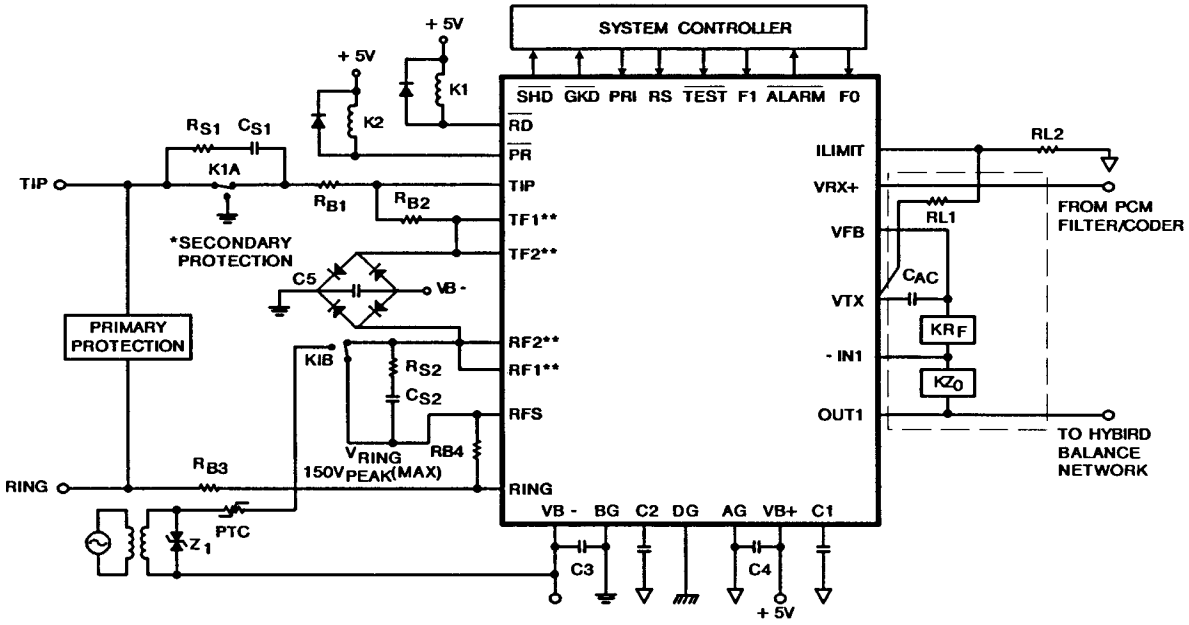
Pin Descriptions (Continued)

DIP	PLCC	SYMBOL	DESCRIPTION
15	24	RING	An analog input connected to the RING (more negative) side of the subscriber loop through a feed resistor. Functions with the TIP terminal to receive voice signals from the telephone and for loop monitoring purposes.
16	25	RFS	Ring Feed Sense - Senses RING side of the loop for Ground Key Detection. During Ring injected ringing the ring signal at this node is isolated from RF via the ring relay. For Tip injected ringing, the RF and RFS pins must be shorted.
17	27	VRX	Receive Input, Four Wire Side - A high impedance analog input. A.C. signals appearing at this input drive the Tip Feed and Ring Feed amplifiers differentially.
18	31	C2	Capacitor #2 - An external capacitor to be connected between this terminal and ground. It prevents false ring trip detection from occurring when longitudinal currents are induced onto the subscriber loop from power lines and other noise sources. This capacitor should be nonpolarized.
19	32	VTX	Transmit Output, Four Wire Side - A low impedance analog output which represents the differential voltage across TIP and RING Transhybrid balancing must be performed beyond this output to completely implement two to four wire conversion. This output is referenced to analog ground. Since the D.C. level of this output varies with loop current, capacitive coupling to the next stage is necessary.
20	33	PRI	A TTL compatible input used to control $\overline{PR}$. PRI active High = $\overline{PR}$ active low.
21	34	$\overline{PR}$	An active low open collector output. Can be used to drive a Polarity Reversal Relay.
22	35	DG	Digital Ground - To be connected to zero potential. Serves as a reference for all digital inputs and outputs on the SLIC.
23	36	$\overline{RD}$	Ring Relay Driver - An active low open collector output. Used to drive a relay that switches ringing signals onto the 2 wire line.
24	37	VFB	Feedback signal from the tip feed amplifier. To be used in conjunction with transmit output signal and the spare op-amp to accommodate 2W line impedance matching.
25	38	TF2	Tip Feed - A low impedance analog output connected to the TIP terminal through a feed resistor. Functions with the RF terminal to provide loop current, and to feed voice signals to the telephone set and to sink longitudinal currents. Must be tied to TF1.
NA	39	TF1	Tie directly to TF2 in the PLCC application.
26	41	RF1	Ring Feed - A low impedance analog output connected to the RING terminal through a feed resistor. Functions with the TF terminal to provide loop current, feed voice signals to the telephone set, and to sink longitudinal currents. Tie directly to RF2.
NA	42	RF2	Tie directly to RF1 in the PLCC application.
27	43	VB-	The battery voltage source. The most negative supply.
28	44	BG	Battery Ground - To be connected to zero potential. All loop current and some quiescent current flows into this ground terminal.
	5, 6, 7, 1, 21, 26, 23, 30, 28, 29, 40, 14, 15, 16	NC	No internal connection.

NOTE: All grounds (AG, BG, DG) must be applied before VB+ or VB-. Failure to do so may result in premature failure of the part. If a user wishes to run separate grounds off a line card, the AG must be applied first.

Applications Diagram 1

TYPICAL LINE CIRCUIT APPLICATION WITH THE HC-5509B



TYPICAL COMPONENT VALUES

C1 = 0.5µF,30V

C2 = 0.5µF-1.0µF ±10%, 20V (Should be nonpolarized)

C3 = 0.01µF, 100V ±20%

C4 = 0.01µF, 100V ±20%

C5 = 0.01µF, 100V ±20%

C_{AC} = 0.5µF, 20V

KZ_0 = 60K, (Z_0 = 600Ω, K = Scaling Factor = 100)

RL1, RL2; Current Limit Setting Resistors

RL1+RL2 > 90kΩ

ILIMIT = 0.6 (RL1+RL2)/200 RL2, RL1 typically 100kΩ

KR_F = 20K, RF = 2(R_{B2}+R_{B4}), K = Scaling Factor = 100)

$RB_1 = RB_2 = RB_3 = RB_4$ = 50Ω (1% absolute, matching requirements covered in a Tech Brief)

$R_{S1} = R_{S2}$ = 1kΩ typically

CS1 = CS2 = 0.1µF, 200V typically, depending on V_{Ring} and line length.

Z_1 = 150V to 200V transient protector. PTC used as ring generator ballast.

* Secondary protection diode bridge recommended is 3A, 200V type.

** TF1, TF2 and RF1, RF2 are on PLCC only and should be connected together as shown.

NOTE: HC-5509B Applications Diagram shows Ring injected ringing configuration. A Balanced or Tip injected configuration may also be used.

Overvoltage Protection
Longitudinal Current Protection

The SLIC device, in conjunction with an external protection bridge, will withstand high voltage lightning surges and power line crosses.

High voltage surge conditions are as specified in Table 2.

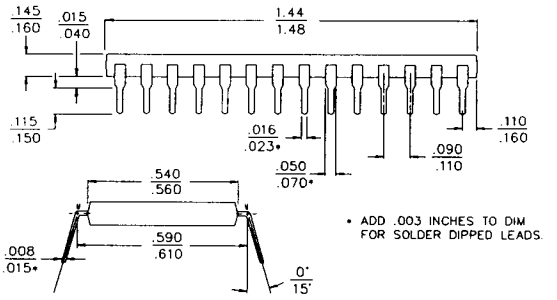
The SLIC will withstand longitudinal currents up to a maximum of 30mArms, 15mArms per leg, without any performance degradation.

TABLE 2.

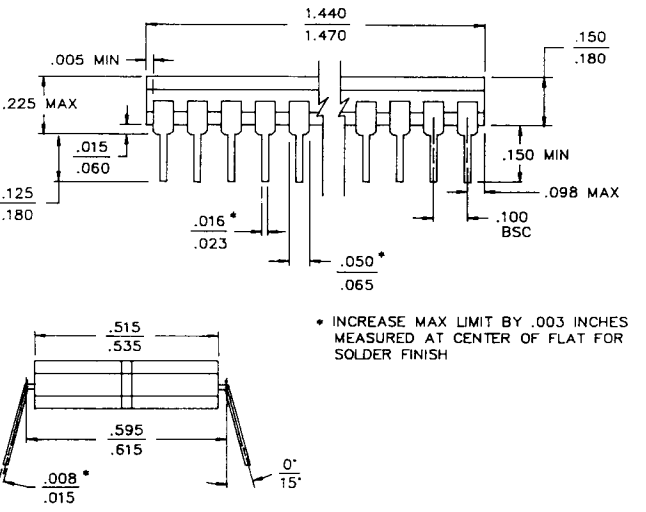
PARAMETER	TEST CONDITION	PEFORMANCE (MAX)	UNITS
Longitudinal Surge	10µs Rise/ 1000µs/Fall	±1000 (Plastic) ±500 (Ceramic)	V_{P-P} V_{P-P}
Metallic Surge	10µs Rise/ 1000µs Fall	±1000 (Plastic) ±500 (Ceramic)	V_{P-P} V_{P-P}
T/GND R/GND	10µs Rise/ 1000µs Fall	±1000 (Plastic) ±500 (Ceramic)	V_{P-P} V_{P-P}
50/60Hz Current T/GND R/GND	700Vrms Limited to 10Arms	11 (Plastic)	Cycles

Packaging

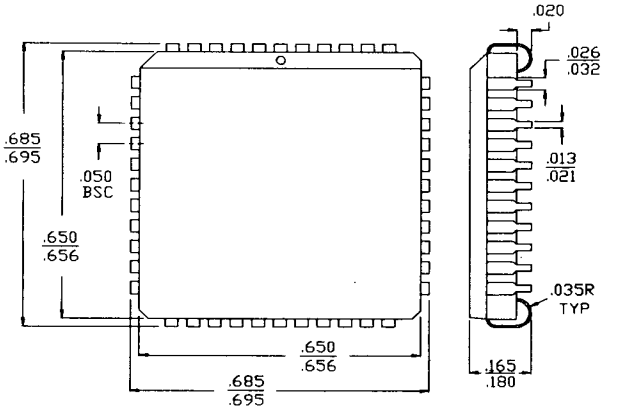
28 LEAD CERAMIC DIP



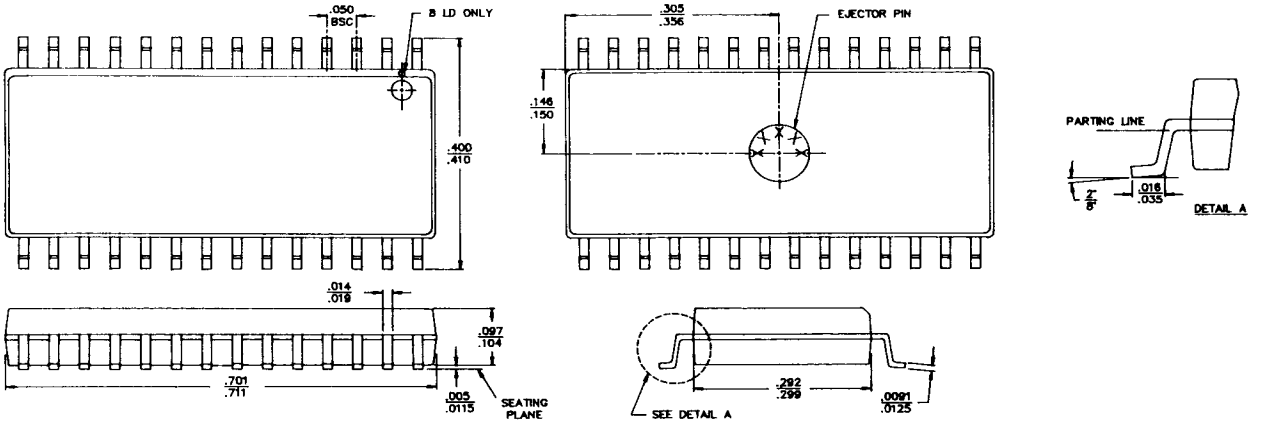
28 LEAD PLASTIC DIP



44 LEAD PLCC



28 LEAD SOIC



NOTE: All Dimensions are $\frac{\text{Min}}{\text{Max}}$, Dimensions are in inches.

Ordering Information

MODEL NUMBER	OPERATING TEMPERATURE RANGE	PRODUCT DESCRIPTION
HC3-5509B-5	0°C to +75°C	Plastic Package, 28 Pin DIP
HC1-5509B-5	0°C to +75°C	Ceramic Package, 28 Pin DIP
HC1-5509B-9	-40°C to +85°C	Ceramic Package, 28 Pin DIP Tested Over Operating Temperature Range
HC4P5509B-5	0°C to +75°C	Plastic Leaded Chip Carrier, 44 Pin (PLCC)
HC3-5509B-9	-40°C to +85°C	Plastic Package, 28 Pin DIP Tested Over Operating Temperature Range
HC4P5509B-9	-40°C to +85°C	Plastic Leaded Chip Carrier (44 Pin PLCC) Tested Over Operating Temperature Range
HC9P5509B-9	-40°C to +85°C	Plastic Small Outline IC 28 Pin SOIC Tested Over Operating Temperature Range
HC9P5509B-5	0°C to +75°C	Plastic Small Outline IC 28 Pin SOIC